

RADIATION SENSITIVE RESIN COMPOSITION, MATERIAL FOR FORMING BUMP AND FOR FORMING WIRING AND DRY FILM RESIST

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Inventor: HIROSE KOICHI; MICHINO YOSHIYUKI; KIMURA TORU; ITAI SHINGO; OTA TOSHIYUKI; YOKOYAMA YASUAKI; SATO HOZUMI
Applicant: JSR CORP
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Abstract of JP2000039709

PROBLEM TO BE SOLVED: To obtain a radiation sensitive resin compsn. suitable for use as a material for forming a bump and for forming wiring.

SOLUTION: The radiation sensitive resin compsn. contains (A) an alkali-soluble copolymer consisting of (a) constituent units derived from a radical polymerizable compd. having a carboxyl group, (b) constituent units derived from a radical polymerizable compd. having a phenolic hydroxyl group and (c) constituent units derived from other radical polymerizable compd., (B) a compd. having at least one ethylenically unsatd. double bond and (C) a radiation radical polymn. initiator.

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